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| 09/607,219 | 06/30/2000 | Atsushi Kanda | 15.18/5053 | 8200 |
| 24033 | 7590 01/12/2004 | | EXAMINER | |
| KONRAD RAYNES VICTOR & MANN, LLP | | | QUACH, TUAN N | |
| SUITE 210 | BEVERLY DRIVE | | ART UNIT | PAPER NUMBER |
| BEVERLY HI | ILLS, CA 90212 | | 2814 | |

DATE MAILED: 01/12/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

| | Application No. | Applicant(s) | |
|--|---|--|---|
| | 09/607,219 | KANDA, ATSUSHI | |
| Office Action Summary | Examiner | Art Unit | |
| | Tuan Quach | 2814 | |
| The MAILING DATE of this communicate Period for Reply | ion appears on the cover shee | with the correspondence address | _ |
| A SHORTENED STATUTORY PERIOD FOR THE MAILING DATE OF THIS COMMUNICATORY Extensions of time may be available under the provisions of 37 after SIX (6) MONTHS from the mailing date of this communicator of the period for reply specified above is less than thirty (30) dator of NO period for reply is specified above, the maximum statutor Failure to reply within the set or extended period for reply will, I Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b). | FION. CFR 1.136(a). In no event, however, maition. ys, a reply within the statutory minimum of y period will apply and will expire SIX (6) to y statute, cause the application to become | y a reply be timely filed thirty (30) days will be considered timely. WONTHS from the mailing date of this communication. e ABANDONED(35 U.S.C.§ 133) | |
| 1) Responsive to communication(s) filed or | n <u>20 October 2003</u> . | | |
| 2a)⊠ This action is FINAL . 2b)□ | This action is non-final. | | |
| 3) Since this application is in condition for closed in accordance with the practice u | | | |
| Disposition of Claims | | | |
| 4) ∠ Claim(s) 48,49 and 52-90 is/are pending 4a) Of the above claim(s) 48,49,52-63 and 5) ☐ Claim(s) is/are allowed. 6) ∠ Claim(s) 64-67 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction | nd 68-90 is/are withdrawn from | n consideration. | |
| Application Papers | | | |
| 9)☐ The specification is objected to by the Example 10)☑ The drawing(s) filed on 30 June 2000 is/ Applicant may not request that any objection Replacement drawing sheet(s) including the 11)☐ The oath or declaration is objected to by | are: a)⊠ accepted or b)□ o to the drawing(s) be held in abe correction is required if the draw | yance. See 37 CFR 1.85(a). ring(s) is objected to. See 37 CFR 1.121(d). | |
| Priority under 35 U.S.C. §§ 119 and 120 | | | |
| 12) △ Acknowledgment is made of a claim for a) △ All b) ☐ Some * c) ☐ None of: 1. △ Certified copies of the priority doc 2. ☐ Certified copies of the priority doc 3. ☐ Copies of the certified copies of the application from the International * See the attached detailed Office action for 13) ☐ Acknowledgment is made of a claim for d since a specific reference was included in 37 CFR 1.78. a) ☐ The translation of the foreign languated acknowledgment is made of a claim for d reference was included in the first sentence. | cuments have been received in the priority documents have been received in the priority documents have been bureau (PCT Rule 17.2(a)). In a list of the certified copies recommended in the first sentence of the spectage provisional application has omestic priority under 35 U.S. | n Application No een received in this National Stage not receivedC. § 119(e) (to a provisional application) effication or in an Application Data Sheet. s been receivedC. §§ 120 and/or 121 since a specific | |
| Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-93) Information Disclosure Statement(s) (PTO-1449) Paper | 948) 5) Notice | ew Summary (PTO-413) Paper No(s) of Informal Patent Application (PTO-152) | |

Art Unit: 2814

DETAILED ACTION

The response to election/restriction required filed October 20, 2003 has been received. Claims 64-67 are elected without traverse. The Information Disclosure Statement filed July 17, 2003 has also been received.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

For convenience, "et al." is omitted, e.g., Chen for Chen et al.

Claims 64-67 are rejected under 35 U.S.C. 103(a) as being unpatentable over Bach taken with Chen and Hall.

Bach teaches forming dielectric layers 18 and 20 of oxide and nitride on metal line 16/17, forming photoresist 24 thereon, etching the dielectric layers to form tapered openings. The use of fluorine compound such as CF_4 or SF_6 as etchant and the inclusion of oxygen are also taught wherein such oxygen addition serves to control the tapered shape. See column 4 line 61 to column 5 line 23, column 7 line 1-3, column 8 lines 11-67. Back does not recite the identical language of pad.

Chen teaches pad 16, passivation 20 comprising silicon oxide 20A and silicon nitride 20B, forming photoresist mask 22, dry etching the passivation 20 to the pad 16, including isotropic etching and anisotropic etching to prevent erosion of photoresist to prevent penetration and attach of passivation over wiring lines. The use of fluorine

Art Unit: 2814

containing etchant and fluorocarbon etchant is also taught. See the abstract, Fig. 4, column 3 line 40 to column 5 line 32.

Hall also teaches the provision of pad 22 interconnect 24 from interconnecting layer 12, which is formed from the interconnect layer followed by passivation layer 42 including oxide 422 and nitride layer 424 and the etching therethrough using dry etching including the use of suitable fluorine containing materials carbon tetrafluoride. The use of carbon tetrafluoride and oxygen is also tuaght. See column 2 line 7 to column 3 line 27.

It would have been obvious to one skilled in practicing Bach to have employed the metal line to be the aluminum pad since such corresponds to conventional language and structure for such aluminum structure as pad as evidenced by Chen or Hall wherein such pad application and opening thereto can be obtained. The use of isotropic etching would have been obvious and advantageous as taught by Chen wherein penetration and attack of the passivation over the wiring lines can be obviated. It would have been obvious and would have been within the purview of one skilled in the art to have employed the desired profiles including a desired angle the upper layer and a steeper angle for the lower layer if desired as evidenced in Chen, to have optimized the appropriate distance to improve device packing. Conversely, although Chen recites NF₃ as etchant of the nitride, the use of CF₄ as alternative fluorine containing materials would have been obvious to one skilled in the art as evidenced by Hall, column 3 lines 18-23, including its oxygen inclusion as delineated in Hall, column 2 line 66 and in Bach as delineated above evidencing the interchangeability of such fluorine containing

Art Unit: 2814

sources including the use of oxygen. It would have been conventional and obvious to have effected continuous etching given the teachings delineated above wherein no discontinuation is required or so that such discontinuation may be minimized. The completion of the connection including the provision of a bump electrode including a barrier on the exposed bonding pad is well known in the art and thus would have been obvious.

Applicant's arguments filed July 3, 2003 have been fully considered but they are not persuasive.

Applicant argues that Bach relates to vias between wiring layers and does not relate to pad structures. Applicant however has not pointed out any supporting portion wherein Bach precludes application to such pad structures. This is further refuted by a comparison between Fig. 1, structure 16, column 4 line 1-3 and the instant disclosure, Fig. 1, structure 2. Furthermore, the etching process primarily relates to that of the dual insulating layers as taught in Bach. Although Bach does not explicitly employ the "pad" language, such application would have been obvious as evidenced by Chen as delineated above, pad structure 6 wherein such structure can be passivated by dual insulating layer 20 comprising silicon oxide 20A and silicon nitride 20B, and wherein such etching can be effected by forming photoresist mask 22, dry etching the passivation 20 to the pad 16, including isotropic etching and anisotropic etching to prevent erosion of photoresist to prevent penetration and attach of passivation over wiring lines. The use of fluorine containing etchant and fluorocarbon etchant is also taught; See the abstract, Fig. 4, column 1 lines 33-35, column 3 line 40 to column 5 line

Art Unit: 2814

32. Such is also taught in Hall which shows the provision of pad 22 interconnect 24 from interconnecting layer 12, which is formed from the interconnect layer followed by passivation layer 42 including oxide 422 and nitride layer 424 and the etching therethrough using dry etching including the use of suitable fluorine containing materials carbon tetrafluoride. The use of carbon tetrafluoride and oxygen is also taught. See column 2 line 7 to column 3 line 27. It remains that such provision of the dual insulating layer on the pad structure would have been obvious as amply evidenced by Chen and Hall.

Applicant argues that the use of isotropical etching is not taught. Nonetheless such use is advantageous as shown in Chen, Figs. 3-4, structure 32, the abstract, column 4 line 17-37 wherein isotropic etching and anisotropic etching are advantageously employed.

Applicant further argues that one skill in the art would be motivated to form openings at right angles to the pad instead of having upper and lower with different angles. This however overlooks the teaching in Chen wherein the different angles between the lower and upper layers are evident and wherein the different angles between the lower and upper layers are shown, e.g., Fig. 4.

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not

mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to examiner Quach whose telephone number is (703)308-1096 (after 1/12/04 (571)272-1717). The examiner can normally be reached on M - F from 9 to 5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor Wael Fahmy can be reached on (703) 308-4918 (after 1/12/04 (571)272-1705). The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9318 (Before Final) and (703) 872-9319 (After Final).

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703)308-0956 (after 1/15/04 (571)272-1562).

16